

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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 $P_{DC}$ 



N-Channel Enhancement Mode Low Q<sub>g</sub> and R<sub>g</sub> High dv/dt Nanosecond Switching

Symbol	Test Conditions	Maximum Ratings		
<b>V</b> <sub>DSS</sub>	T <sub>J</sub> = 25°C to 150°C	1000	V	
$\mathbf{V}_{DGR}$	$T_J$ = 25°C to 150°C; $R_{GS}$ = 1 $M\Omega$	1000	V	
<b>V</b> <sub>GS</sub>	Continuous	±20	V	
$\mathbf{V}_{GSM}$	Transient	±30	V	
I <sub>D25</sub>	T <sub>c</sub> = 25°C	2	Α	
$I_{DM}$	$T_c$ = 25°C, pulse width limited by $T_{\text{JM}}$	12	Α	
I <sub>AR</sub>	T <sub>c</sub> = 25°C	1.5	Α	
<b>E</b> <sub>AR</sub>	T <sub>c</sub> = 25°C	6	mJ	
dv/dt	$\begin{split} &I_{S} \leq I_{DM}, \ di/dt \leq ^{\sim} 100 A/\mu s, \ V_{DD} \leq V_{DSS}, \\ &T_{j} \leq 150^{\circ} C, \ R_{G} = 0.2 \Omega \end{split}$	3	V/ns	
	I <sub>S</sub> = 0	>200	V/ns	
P <sub>DC</sub>		200	W	
P <sub>DHS</sub>	T <sub>c</sub> = 25°C Derate .7W/°C above 25°C	105	W	
P <sub>DAMB</sub>	T <sub>c</sub> = 25°C	3.5	W	
R <sub>thJC</sub>		0.71	C/W	
$R_{\text{thJHS}}$		1.41	C/W	

Symbol	Test Conditions	Characteristic Values T <sub>J</sub> = 25°C unless otherwise specified

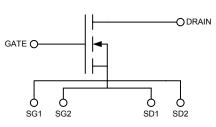
		min.	typ.	max.	
V <sub>DSS</sub>	$V_{GS} = 0 \text{ V}, I_{D} = 3 \text{ ma}$	1000			V
$V_{GS(th)}$	$V_{DS} = V_{GS}$ , $I_D = 4$ ma	2.5		4.5	V
I <sub>GSS</sub>	$V_{GS} = \pm 20 \ V_{DC}, \ V_{DS} = 0$			±100	nΑ
I <sub>DSS</sub>	$V_{DS} = 0.8 V_{DSS} T_J = 25^{\circ}C$ $V_{GS} = 0$ $T_J = 125^{\circ}C$			50 500	μ <b>Α</b> μ <b>Α</b>
R <sub>DS(on)</sub>	$V_{GS}$ = 15 V, $I_D$ = 0.5 $I_{D25}$ Pulse test, t $\leq$ 300 $\mu$ S, duty cycle d $\leq$ 2%			7.8	Ω
<b>g</b> fs	$V_{DS}$ = 15 V, $I_D$ = 0.5 $I_{D25}$ , pulse test	0.8	2		S
T <sub>J</sub>		-55		+175	°C
T <sub>JM</sub>			175		°C
<b>T</b> <sub>stg</sub>		-55		+175	°C
T <sub>L</sub>	1.6mm (0.063 in) from case for 10 s		300		°C
Weight			2		g

 $V_{DSS}$  = 1000 V  $I_{D25}$  = 2 A  $R_{DS(on)}$  = 7.8  $\Omega$ 

=

200W





## **Features**

- Isolated Substrate
- high isolation voltage (>2500V)
- excellent thermal transfer
- Increased temperature and power cycling capability
- IXYS advanced low Q<sub>g</sub> process
- Low gate charge and capacitances
- easier to drive
- faster switching
- Low R<sub>DS(on)</sub>
- Very low insertion inductance (<2nH)
- No beryllium oxide (BeO) or other hazardous materials

### **Advantages**

- Optimized for RF and high speed switching at frequencies to 30MHz
- Easy to mount—no insulators needed
- High power density

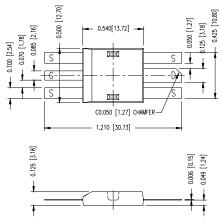


## **Symbol Test Conditions**

## **Characteristic Values**

(T<sub>J</sub> = 25°C unless otherwise specified)

	min.	typ.	max.
$R_{G}$			5 Ω
C <sub>iss</sub>		500	pF
Coss	$V_{GS}$ = 0 V, $V_{DS}$ = 0.8 $V_{DSS(max)}$ , f = 1 MHz	150	pF
C <sub>rss</sub>		3	pF
<b>C</b> <sub>Stray</sub>	Back Metal to any Pin	16	pF
T <sub>d(on)</sub>		4	ns
$\mathbf{T}_{on}$	$V_{GS} = 15 \text{ V}, V_{DS} = 0.8 \text{ V}_{DSS}$ $I_D = 0.5 \text{ I}_{DM}$	4	ns
$\mathbf{T}_{d(off)}$	$R_G = 0.2 \Omega$ (External)	4	ns
<b>T</b> off		4	ns
<b>Q</b> g(on)		23	nC
$\mathbf{Q}_{gs}$	$V_{GS}$ = 10 V, $V_{DS}$ = 0.5 $V_{DSS}$ $I_D$ = 0.5 $I_{D25}$	4.5	nC
$\mathbf{Q}_{gd}$		14	nC



### Source-Drain Diode

## **Characteristic Values**

(T<sub>J</sub> = 25°C unless otherwise specified)

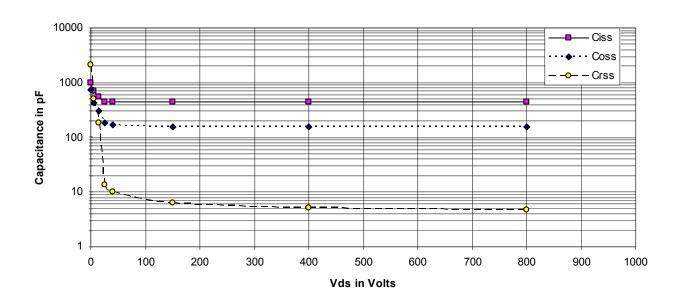
Symbol	Test Conditions	min.	typ.	max.	
Is	V <sub>GS</sub> = 0 V			1.5	Α
I <sub>SM</sub>	Repetitive; pulse width limited by $T_{\text{JM}}$			12	Α
<b>V</b> <sub>SD</sub>	$I_F = I_S,  V_{GS} = 0  V,$ Pulse test, $t \leq 300  \mu s,  duty  cycle \leq 2\%$			1.8	V
T <sub>rr</sub>		·	710		ns

For detailed device mounting and installation instructions, see the "*DE-Series MOSFET Mounting Instructions*" technical note on IXYS RF's web site at www.ixysrf.com/Technical\_Support/App\_notes.html

IXYS RF reserves the right to change limits, test conditions and dimensions. IXYS RF MOSFETS are covered by one or more of the following U.S. patents:

4,835,592	4,850,072	4,881,106	4,891,686	4,931,844	5,017,508
5,034,796	5,049,961	5,063,307	5,187,117	5,237,481	5,486,715
5,381,025	5,640,045				





Capacitances vs Vds



## 102N02A DE-SERIES SPICE Model

The DE-SERIES SPICE Model is illustrated in Figure 1. The model is an expansion of the SPICE level 3 MOSFET model. It includes the stray inductive terms  $L_G$ ,  $L_S$  and  $L_D$ . Rd is the  $R_{DS(ON)}$  of the device, Rds is the resistive leakage term. The output capacitance,  $C_{OSS}$ , and reverse transfer capacitance,  $C_{RSS}$  are modeled with reversed biased diodes. This provides a varactor type response necessary for a high power device model. The turn on delay and the turn off delay are adjusted via Ron and Roff.

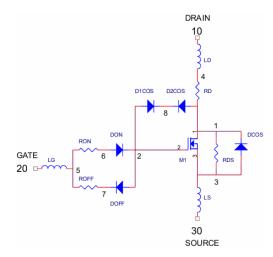


Figure 1 DE-SERIES SPICE Model

This SPICE model may be downloaded as a text file from the DEI web site at www.directedenergy.com/spice.htm

#### Net List:

\*SYM=POWMOSN

.SUBCKT 102N02A 10 20 30

\* TERMINALS: D G S

\* 1000 Volt 1.4 Amp 7.8 ohm N-Channel Power MOSFET 10-30-2000

M1 1 2 3 3 DMOS L=1U W=1U

RON 56 4.0

DON 62 D1

ROF 57 2.0

DOF 27 D1

D1CRS 28 D2

D2CRS 1 8 D2

CGS 23 500Pf

RD 417.8

DCOS 3 1 D3

RDS 13 5.0MEG

LS 330.5N

LD 104 1N

LG 205 1N

.MODEL DMOS NMOS (LEVEL=3 VTO=3 KP=.3)

.MODEL D1 D (IS=.5F CJO=10P BV=100 M=.5 VJ=.2 TT=1N)

.MODEL D2 D (IS=.5F CJO=100P BV=1000 M=.6 VJ=.6 TT=1N RS=10M)

.MODEL D3 D (IS=.5F CJO=150P BV=1000 M=.35 VJ=.6 TT=400N RS=10M) .ENDS

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